TMX IT01

SAW Filter datasheet

3.0 x 3.0 x 1.3 mm, SMD

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Issue: Rev 2, 06 January 2023

TMX IT01

SAW Bandpass Filters | Wireless Communications

Features

Features

- 829 MHz center frequency
- Ceramic package for Surface Mounted Technology
- Low Loss RF Filter: 2.5 dB typical value within PassBand Width 828.80 to 829.20 MHz

Applications

- Remote control - RF
- Wireless applications

3.0 x 3.0 x 1.3 mm

Maximum Ratings

Parameter	Min.	Typ.	Max.	Unit
Storage temperature range (T_{stg})	-45		85	°C
Operating temperature range (T_A)	-40		85	°C
DC Voltage (V_{DC})			12	V
RF Power (in Band Width)			10	dBm

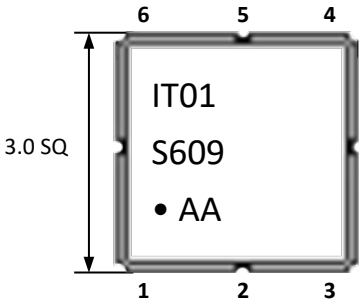
Frequency and Electrical Characteristics (Reference temperature @ 25°C)

Parameter	Min.	Typ.[1]	Max.	Unit
Center frequency (fc)		829		MHz
Bandwidth (BW, passband width)	0.40			MHz
1 dB Bandwidth (BW)	750	900	1200	KHz
Insertion Loss (IL, 828.80 – 829.20 MHz)		2.5	3.5	dB
Amplitude ripple (828.80 – 829.20 MHz)		0.5	1.0	dB
Absolute Attenuation				
From DC to 650.00 MHz	40	45		dB
From 650.00 to 710.00 MHz	38	43		dB
821.00 MHz	30	35		dB
832.00 MHz	26	30		dB
From 840.00 to 850.00 MHz	25	35		dB
From 850.00 to 1000.0 MHz	40	45		dB
Frequency Temperature Coefficent		0.032		ppm/°C[2]
Input Impedance		50		Ω
Output Impedance		50		Ω

[1] Typical values are nominal performances at room temperature

Model Outline, Pin Connection and Marking

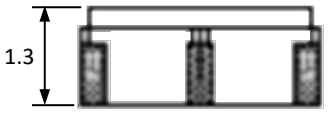
TOP VIEW



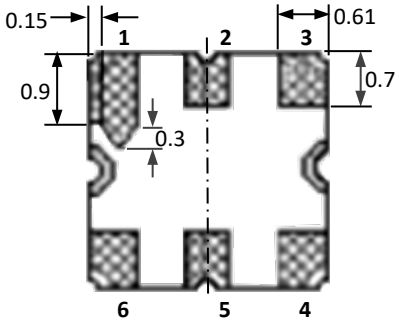
Marking		Note
Line 1	IT01	Rakonxpress designation
Line 2	S609	S = Production code 6 = Year 2016 09 = Week 08
Line 3	•AA	• = Identify black dot AA = Internal Code (Wafer Batch)

Pin	Connections
2	Input
5	Ouptut
1, 3, 4, 6	Ground

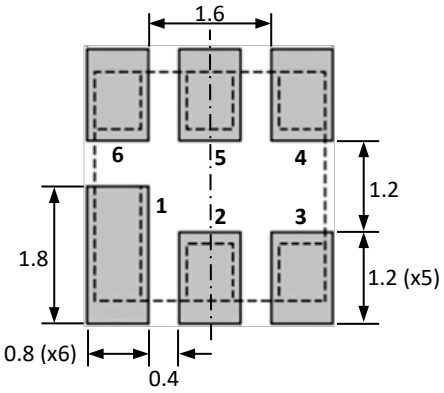
FRONT VIEW



BOTTOM VIEW



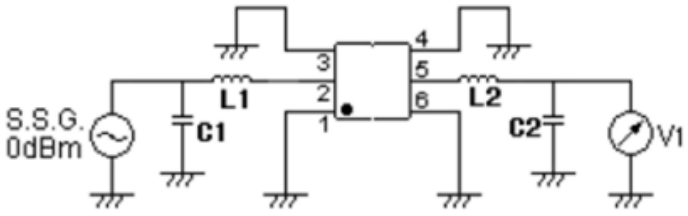
RECOMMENDED PAD LAYOUT
TOP VIEW



Unit: mm

Test Circuit

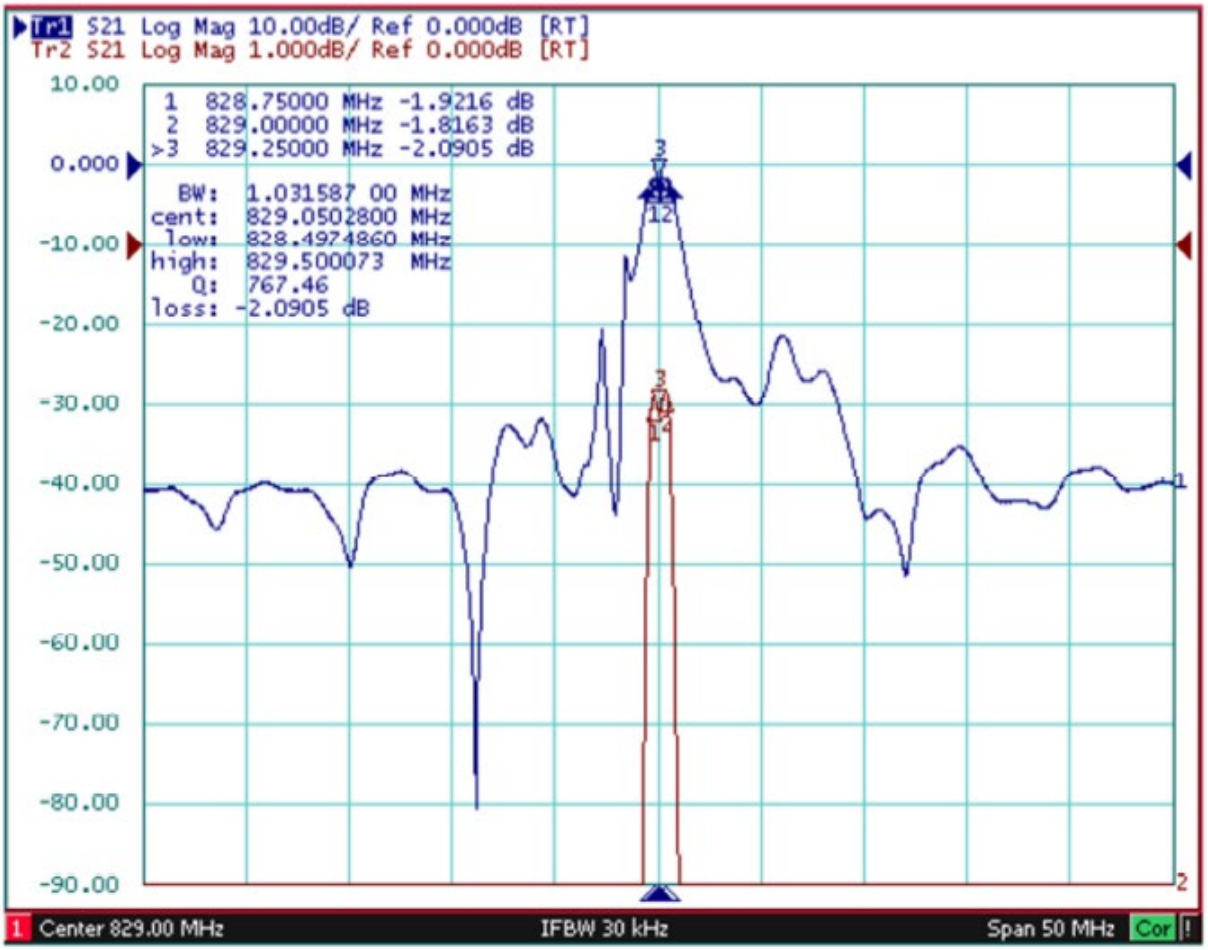
50 Ω / 50 Ω Configuration



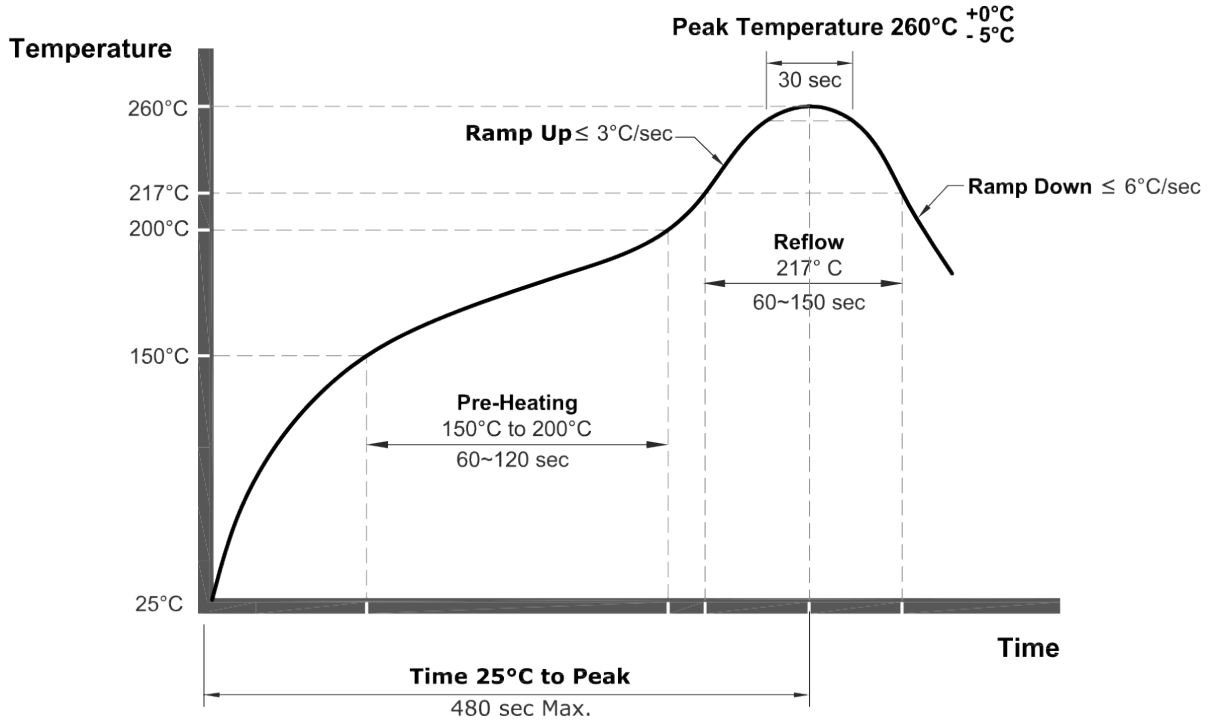
L1=L2=18nH **C1=C2=1.8pF**

Frequency Characteristics

TYPICAL S21 RESPONSE



Recommended Reflow Soldering Profile

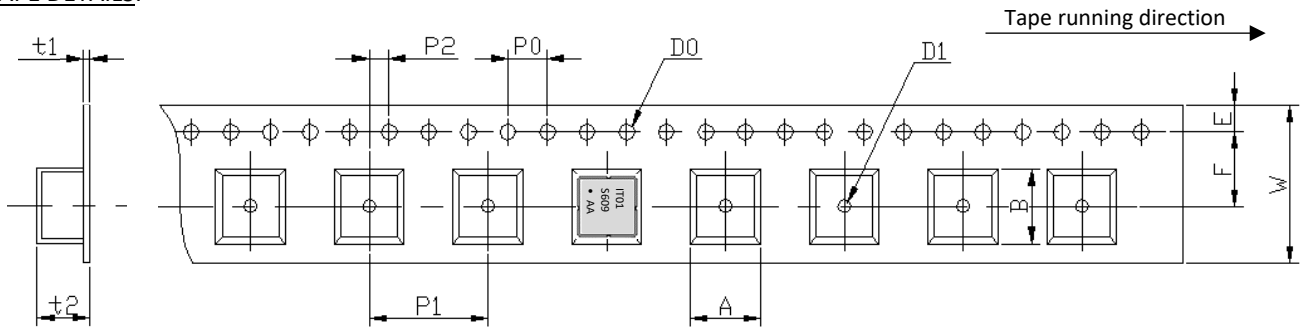


NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at 260 ± 5°C during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350 ± 10 °C during 3~4 seconds. Recovery time: 2 ± 0.5 hour.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of components may be soldered. Please avoid soldering another part of the component.

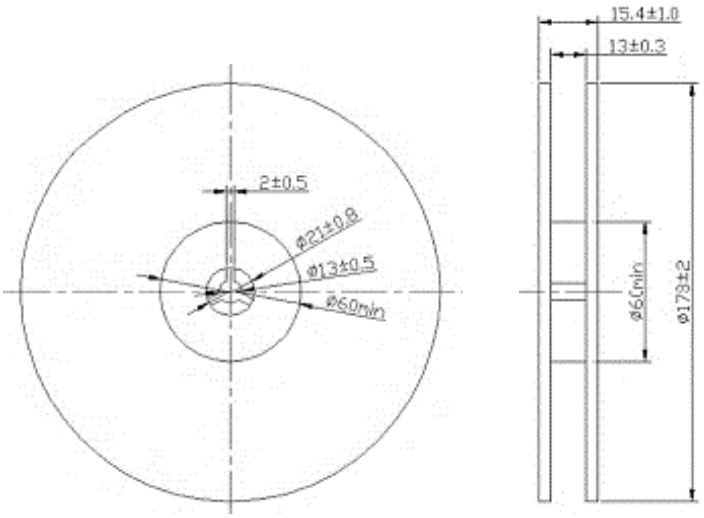
Tape and Reel Specifications

TAPE DETAILS:



Parameter	Code	Dimension	Tolerance
Height of component hole	A	3.3 max	
Width of component hole	B	3.3 max	
Diameter of sprocket hole	D_0	Φ 1.5	± 0.1
Diameter of feed hole	D_1	Φ 1.5	± 0.25
Pitch of sprocket hole	P_0	4.0	± 0.2
Length from hole center to component center	P_1	4.0	± 0.1
Length from Pocket hole center to sprocket hole center	P_2	2.0	± 0.2
Width of carrier tape	W	12.0	± 0.3
Width of adhesive tape	F	5.5	± 0.3
Gap of hold down tape and carrier tape	E	1.75	± 0.1
Thickness of Ebossed tape sheet	t1	0.31 max	
Thickness of Ebossed tape	t2	1.7 max	

REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 3000 pieces/ reel

Reliability Test

Parameter	Test condition / Description
Thermal Shock	The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40° C ±3° C, TB=85° C ±2° C, t1=t2=30min, switch time ≤3min & cycle time: 100 times, recovery time: 2h±0.5h.
Temperature Storage	High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C ±2°C for 500 hours, recovery time: 2h ±0.5h. Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C ±3°C for 500 hours, recovery time: 2h ±0.5h.
Humidity test	The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C ±2°C, and 90~95% RH for 500 hours.
Drop test	The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications.
Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours.
Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6ms.
Note	As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests.